

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Silicon Dual Photodiode Version 1.4

SFH 221



Features:

- Especially suitable for applications from 400 nm to 1100 nm
- · High photosensitivity
- Hermetically sealed metal package (similar to TO-5), suitable up to 125 °C
- · Double diode with extremely high homogeneousness

Applications

- · Industrial electronics
- · For control and drive circuits
- Edge drives
- Follow-up control

Ordering Information

| Туре: | Ordering Code |
|---------|---------------|
| SFH 221 | Q62702P0270 |

Note:: For operating conditions of $T_A > 85$ °C please contact us.



Maximum Ratings $(T_A = 25 \, ^{\circ}C)$

| Parameter | Symbol | Values | Unit |
|--|-------------------|---------|------|
| Operating and storage temperature range | $T_{op}; T_{stg}$ | -40 125 | °C |
| Reverse voltage | V_R | 10 | V |
| Insulation voltage vs. package | V _{IS} | 100 | V |
| Total Power dissipation | P _{tot} | 50 | mW |
| ESD withstand voltage (acc. to ANSI/ ESDA/ JEDEC JS-001 - HBM) | V _{ESD} | 2000 | V |

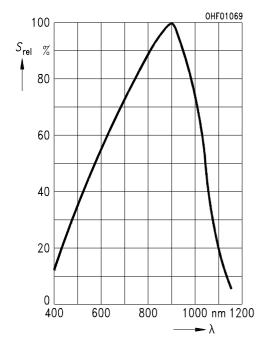
Characteristics ($T_A = 25$ °C, per single diode)

| Parameter | | Symbol | Values | Unit |
|---|-------------|---------------------------------|-------------------|--------------------------|
| Spectral sensitivity (V _R = 5 V, standard light A, T = 2856 K) | (typ) | S | 24 (≥ 15) | nA/lx |
| Wavelength of max. sensitivity | (typ) | $\lambda_{\text{S max}}$ | 900 | nm |
| Spectral range of sensitivity | (typ) | λ _{10%} | (typ) 400 1100 | nm |
| Radiant sensitive area | (typ) | А | 1.54 | mm ² |
| Dimensions of radiant sensitive area | (typ) | LxW | 0.7 x 2.2 | mm x mm |
| Half angle | (typ) | φ | ± 55 | 0 |
| Dark current (V _R = 10 V) | (typ (max)) | I _R | 10 (≤ 100) | nA |
| Spectral sensitivity of the chip $(\lambda = 850 \text{ nm})$ | (typ) | S _{\lambda typ} | 0.55 | A/W |
| Max. deviation from average for each single diode | (typ) | ΔS | ±5 | % |
| Quantum yield of the chip $(\lambda = 850 \text{ nm})$ | (typ) | η | 0.80 | Electro ns /Photon |
| Open-circuit voltage (E _v = 1000 lx, Std. Light A) | (typ (min)) | Vo | 330 (≥ 280) | mV |
| Short-circuit current $(E_v = 1000 \text{ lx}, \text{ Std. Light A})$ | (typ) | I _{SC} | 24 | μΑ |
| Insulation current (V _{IS} = 100 V) | (typ (max)) | I _{IS} | 0.1 (≤ 1) | nA |
| Rise and fall time $(V_R = 5 \text{ V}, R_L = 1 \text{ k}\Omega, \lambda = 850 \text{ nm})$ | (typ) | t _r , t _f | 0.5 | μs |
| Forward voltage (I _F = 40 mA, E = 0) | (typ) | V _F | 1 | V |

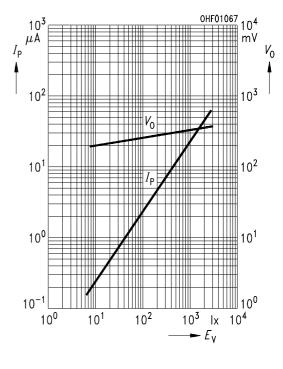


| Parameter | | Symbol | Values | Unit |
|---|-------|-----------------|--------|-----------------------------|
| Capacitance $(V_R = 0 \text{ V}, f = 1 \text{ MHz}, E = 0)$ | (typ) | C ₀ | 25 | pF |
| Temperature coefficient of V _O | (typ) | TC _V | -2.6 | mV / K |
| Temperature coefficient of I _{SC} (Std. Light A) | (typ) | TC _i | 0.18 | % / K |
| Noise equivalent power $(V_R = 10 \text{ V}, \lambda = 850 \text{ nm})$ | (typ) | NEP | 0.103 | pW / Hz ^½ |
| Detection limit $(V_R = 10 \text{ V}, \lambda = 850 \text{ nm})$ | (typ) | D [*] | 1.2e12 | cm x Hz ^½ / W |

Relative Spectral Sensitivity 1) page 7 $S_{rel} = f(\lambda)$

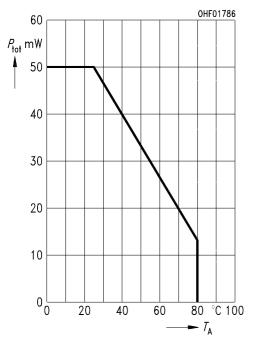


Photocurrent / Open-Circuit Voltage $^{1) page 7}$ $I_P (V_R = 5 \text{ V}) / V_O = f(E_v)$

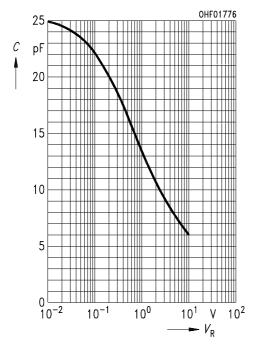


Power Consumption

$$P_{tot} = f(T_A)$$

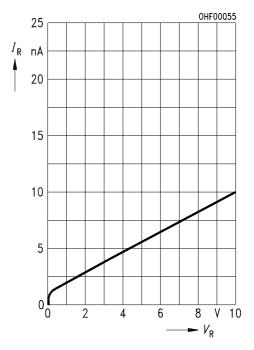


Capacitance 1) page 7 $C = f(V_R)$, f = 1 MHz, E = 0



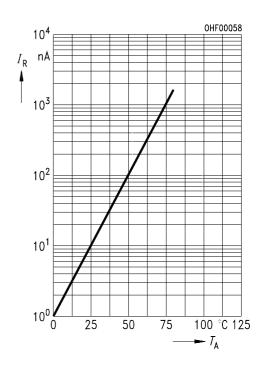
Dark Current 1) page 7

$$I_{R} = f(V_{R}), E = 0$$



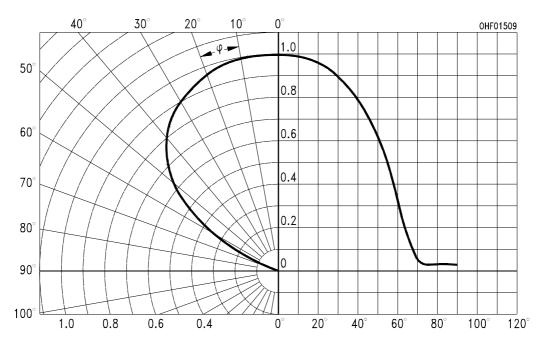
Dark Current 1) page 7

$$I_R = f(T_A), V_R = 10 V, E = 0$$

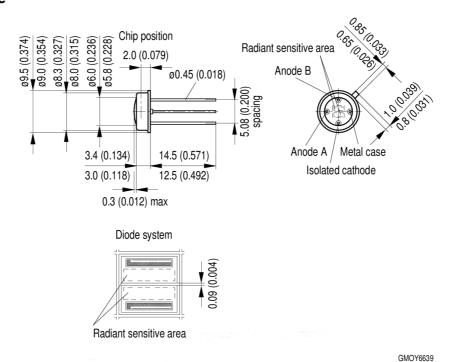


Directional Characteristics 1) page 7

$$S_{rel} = f(\phi)$$



Package Outline



Dimensions in mm (inch).

Package

Metal Can (TO-39), hermetically sealed

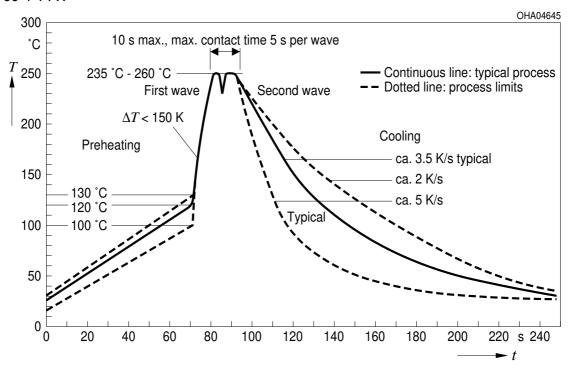


Approximate Weight:

0.8 g

TTW Soldering

IEC-61760-1 TTW



Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics.

Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version in the Internet.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Components used in life-support devices or systems must be expressly authorized for such purpose! Critical components* may only be used in life-support devices** or systems with the express written approval of OSRAM OS.

- *) A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or the effectiveness of that device or system.
- **) Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health and the life of the user may be endangered.



Glossary

Typical Values: Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.



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